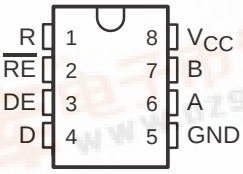
SLLS101B – JULY 1985 – REVISED JUNE 1999

- Bidirectional Transceivers
- Meet or Exceed the Requirements of ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Driver and Receiver Outputs
- Individual Driver and Receiver Enables
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capability . . . ±60 mA Max
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operate From Single 5-V Supply

D OR P PACKAGE
(TOP VIEW)



description

The SN65176B and SN75176B differential bus transceivers are monolithic integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27.

The SN65176B and SN75176B combine a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or V_{CC} = 0. These ports feature wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

The driver is designed for up to 60 mA of sink or source current. The driver features positive and negative current limiting and thermal shutdown for protection from line-fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The receiver features a minimum input impedance of 12 kΩ, an input sensitivity of ±200 mV, and a typical input hysteresis of 50 mV.

The SN65176B and SN75176B can be used in transmission-line applications employing the SN75172 and SN75174 quadruple differential line drivers and SN75173 and SN75175 quadruple differential line receivers.

The SN65176B is characterized for operation from –40°C to 105°C and the SN75176B is characterized for operation from 0°C to 70°C.

Function Tables

DRIVER

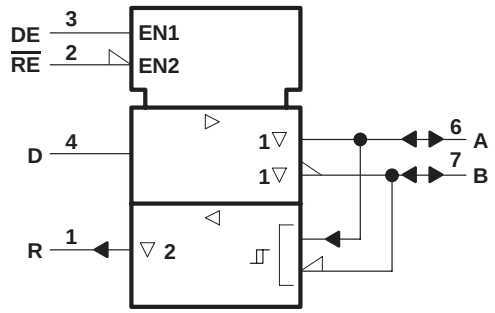
INPUT D	ENABLE DE	OUTPUTS	
		A	B
H	H	H	L
L	H	L	H
X	L	Z	Z

RECEIVER

DIFFERENTIAL INPUTS A–B	ENABLE $\overline{RE}$	OUTPUT R
$V_{ID} \geq 0.2$ V	L	H
-0.2 V $< V_{ID} < 0.2$ V	L	?
$V_{ID} \leq -0.2$ V	L	L
X	H	Z
Open	L	?

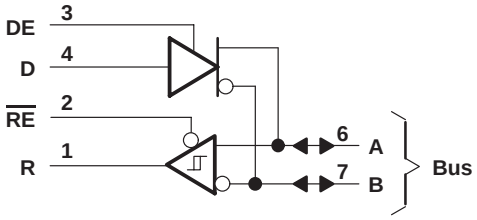
H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

logic symbol†

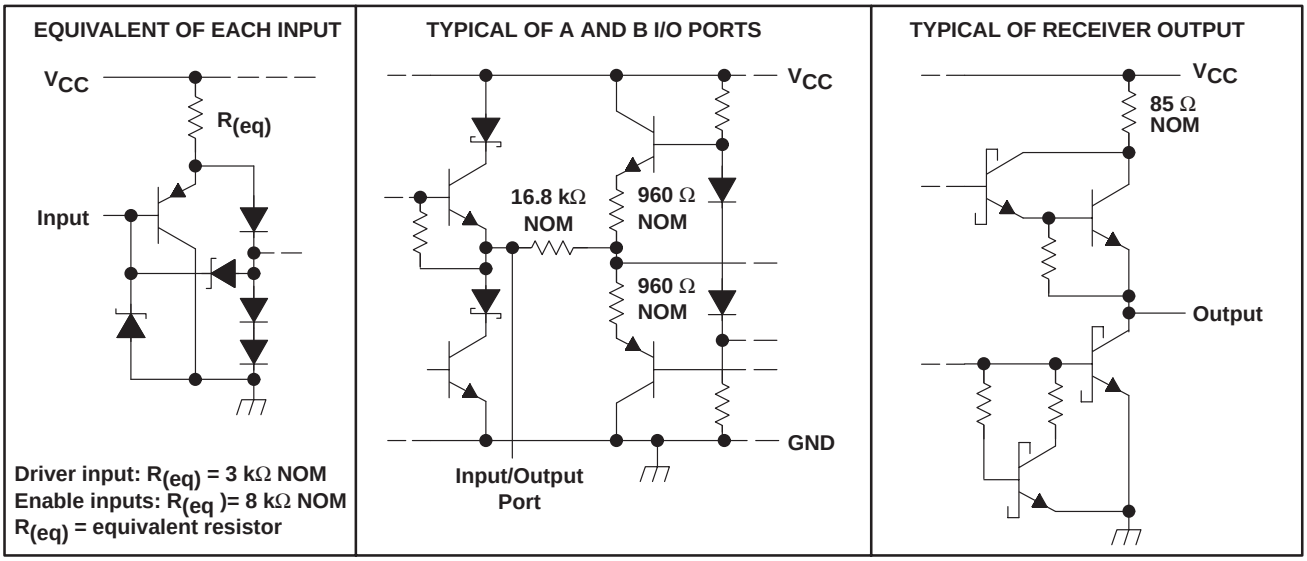


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Voltage range at any bus terminal . . . . . –10 V to 15 V
Enable input voltage, V_I . . . . . 5.5 V
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 197°C/W
P package . . . . . 104°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		MIN	TYP	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus terminal (separately or common mode), V_I or V_{IC}				12	V
				–7	
High-level input voltage, V_{IH}	D, DE, and $\overline{RE}$	2			V
Low-level input voltage, V_{IL}	D, DE, and $\overline{RE}$			0.8	V
Differential input voltage, V_{ID} (see Note 3)				±12	V
High-level output current, I_{OH}	Driver			–60	mA
	Receiver			–400	µA
Low-level output current, I_{OL}	Driver			60	mA
	Receiver			8	
Operating free-air temperature, T_A	SN65176B	–40		105	°C
	SN75176B	0		70	

NOTE 3: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage	I_I = –18 mA				–1.5	V
V_O	Output voltage	I_O = 0		0		6	V
$\|V_{OD1}\|$	Differential output voltage	I_O = 0		1.5	3.6	6	V
$\|V_{OD2}\|$	Differential output voltage	R_L = 100 Ω,	See Figure 1	1/2 V_{OD1} or 2¶			V
		R_L = 54 Ω,	See Figure 1	1.5	2.5	5	V
V_{OD3}	Differential output voltage	See Note 4		1.5		5	V
$\Delta\|V_{OD}\|$	Change in magnitude of differential output voltage§	R_L = 54 Ω or 100 Ω,	See Figure 1			±0.2	V
V_{OC}	Common-mode output voltage					+3 –1	V
$\Delta\|V_{OC}\|$	Change in magnitude of common-mode output voltage§					±0.2	V
I_O	Output current	Output disabled, See Note 5	V_O = 12 V			1	mA
			V_O = – 7 V			–0.8	
I_{IH}	High-level input current	V_I = 2.4 V				20	μA
I_{IL}	Low-level input current	V_I = 0.4 V				–400	μA
I_{OS}	Short-circuit output current	V_O = –7 V				–250	mA
		V_O = 0				150	
		V_O = V_{CC}				250	
		V_O = 12 V				250	
I_{CC}	Supply current (total package)	No load	Outputs enabled		42	70	mA
			Outputs disabled		26	35	

† The power-off measurement in ANSI Standard TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.
‡ All typical values are at V_{CC} = 5 V and T_A = 25°C.
§ $\Delta|V_{OD}|$ and $\Delta|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
¶ The minimum V_{OD2} with a 100-Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.
NOTES: 4. See ANSI Standard TIA/EIA-485-A, Figure 3.5, Test Termination Measurement 2.
5. This applies for both power on and off; refer to ANSI Standard TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

switching characteristics, V_{CC} = 5 V, R_L = 110 kΩ, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{d(OD)}$	Differential-output delay time	R_L = 54 Ω,	See Figure 3		15	22	ns
$t_{t(OD)}$	Differential-output transition time				20	30	ns
t_{PZH}	Output enable time to high level	See Figure 4			85	120	ns
t_{PZL}	Output enable time to low level	See Figure 5			40	60	ns
t_{PHZ}	Output disable time from high level	See Figure 4			150	250	ns
t_{PLZ}	Output disable time from low level	See Figure 5			20	30	ns

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
V_O	V_{oa}, V_{ob}	V_{oa}, V_{ob}
$\|V_{OD1}\|$	V_o	V_o
$\|V_{OD2}\|$	V_t (R_L = 100 Ω)	V_t (R_L = 54 Ω)
$\|V_{OD3}\|$		V_t (Test Termination Measurement 2)
$\Delta\|V_{OD}\|$	$\|\ \|V_t\| - \|\overline{V}_t\|\ \|$	$\|\ \|V_t - \|\overline{V}_t\|\ \|$
V_{OC}	$\|V_{os}\|$	$\|V_{os}\|$
$\Delta\|V_{OC}\|$	$\|V_{os} - \overline{V}_{os}\|$	$\|V_{os} - \overline{V}_{os}\|$
I_{OS}	$\|I_{sa}\|$, $\|I_{sb}\|$	
I_O	$\|I_{xa}\|$, $\|I_{xb}\|$	I_{ia}, I_{ib}

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V_O = 2.7 V,	I_O = –0.4 mA			0.2	V
V_{IT-}	Negative-going input threshold voltage	V_O = 0.5 V,	I_O = 8 mA	–0.2‡			V
V_{hys}	Input hysteresis voltage ($V_{IT+} - V_{IT-}$)				50		mV
V_{IK}	Enable Input clamp voltage	I_I = –18 mA				–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 200 mV, See Figure 2	I_{OH} = –400 μA,	2.7			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV, See Figure 2	I_{OL} = 8 mA,			0.45	V
I_{OZ}	High-impedance-state output current	V_O = 0.4 V to 2.4 V				±20	μA
I_I	Line input current	Other input = 0 V, See Note 6	V_I = 12 V			1	mA
			V_I = –7 V			–0.8	
I_{IH}	High-level enable input current	V_{IH} = 2.7 V				20	μA
I_{IL}	Low-level enable input current	V_{IL} = 0.4 V				–100	μA
r_I	Input resistance	V_I = 12 V		12			kΩ
I_{OS}	Short-circuit output current			–15		–85	mA
I_{CC}	Supply current (total package)	No load	Outputs enabled		42	55	mA
			Outputs disabled		26	35	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.
NOTE 6: This applies for both power on and power off. Refer to EIA Standard TIA/EIA-485-A for exact conditions.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	V_{ID} = 0 to 3 V, See Figure 6		21	35	ns
t_{PHL}	Propagation delay time, high- to low-level output			23	35	ns
t_{PZH}	Output enable time to high level	See Figure 7		10	20	ns
t_{PZL}	Output enable time to low level			12	20	ns
t_{PHZ}	Output disable time from high level	See Figure 7		20	35	ns
t_{PLZ}	Output disable time from low level			17	25	ns

PARAMETER MEASUREMENT INFORMATION

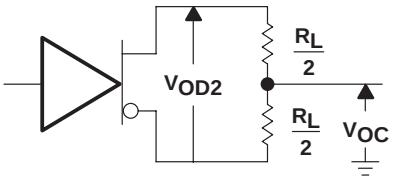


Figure 1. Driver V_{OD} and V_{OC}

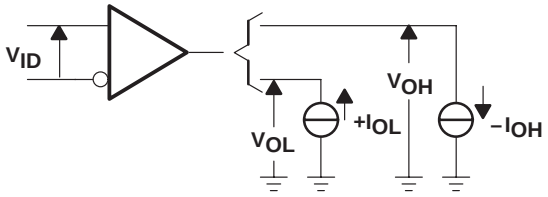
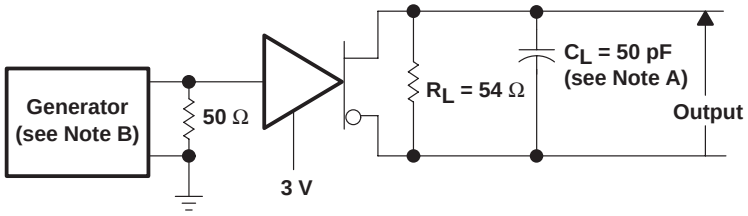
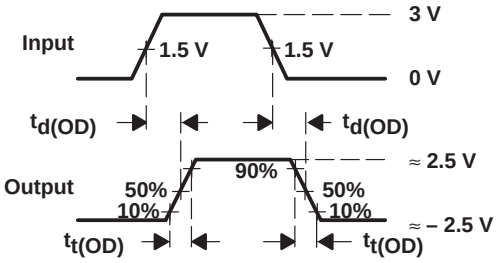


Figure 2. Receiver V_{OH} and V_{OL}



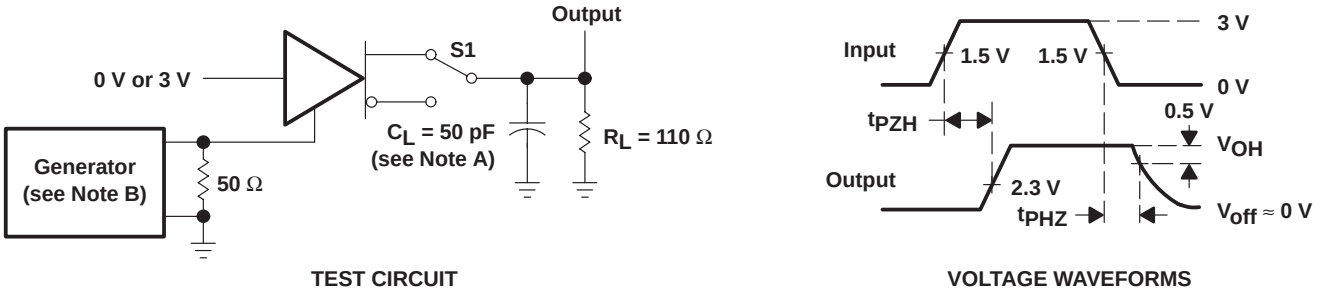
TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

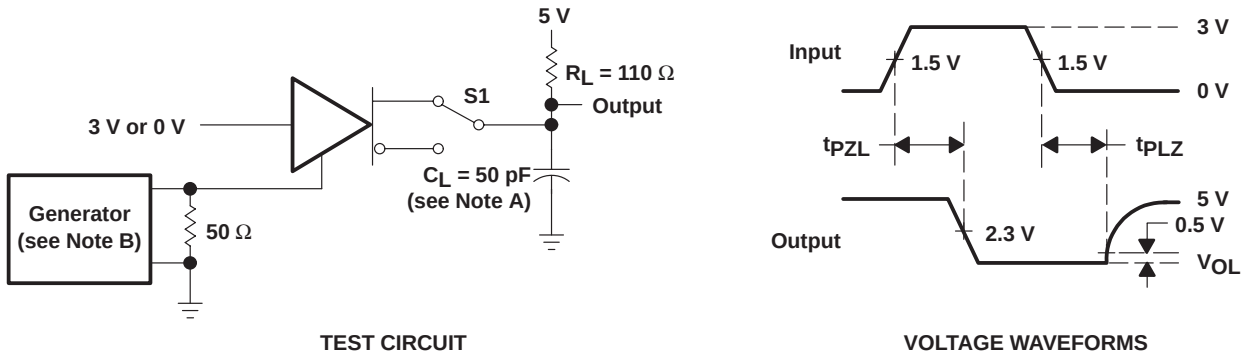
Figure 3. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

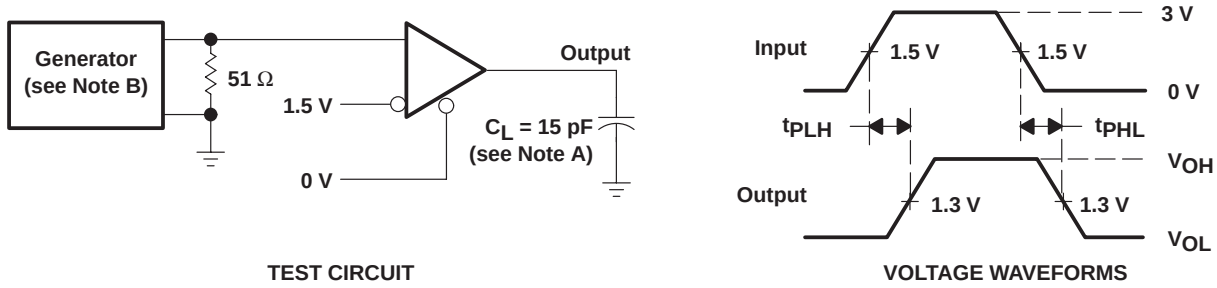
Figure 4. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 5. Driver Test Circuit and Voltage Waveforms

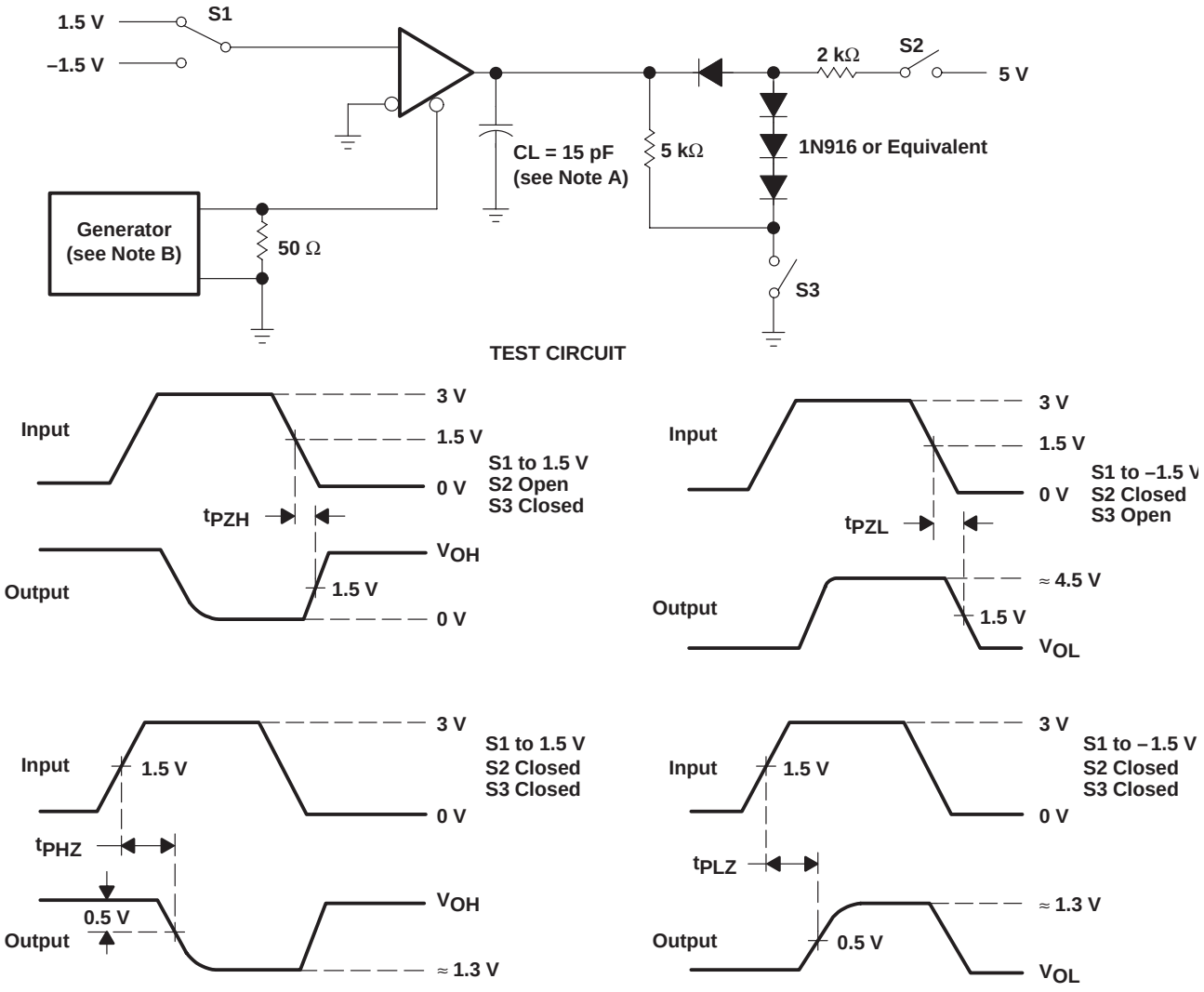


TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 6. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 7. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

DRIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

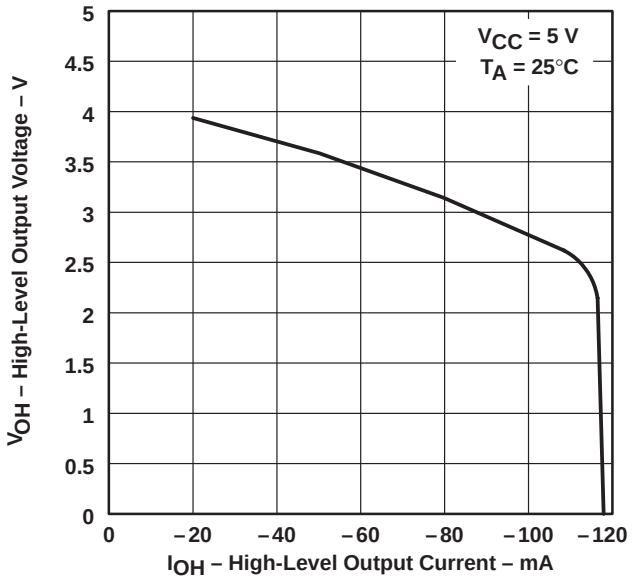


Figure 8

DRIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

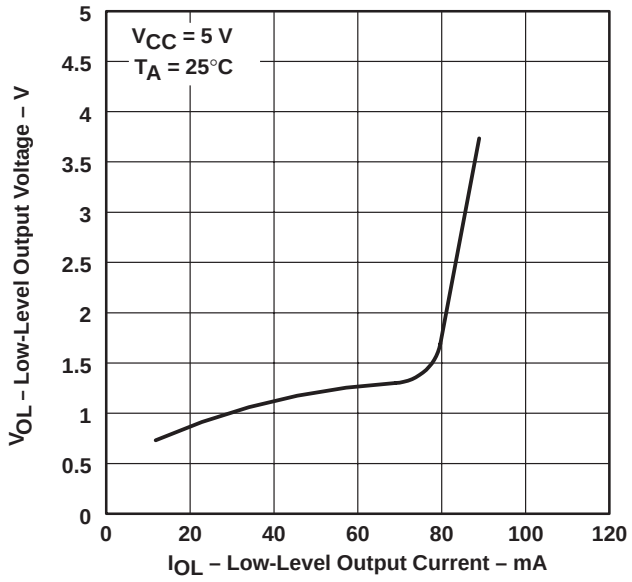


Figure 9

DRIVER
DIFFERENTIAL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

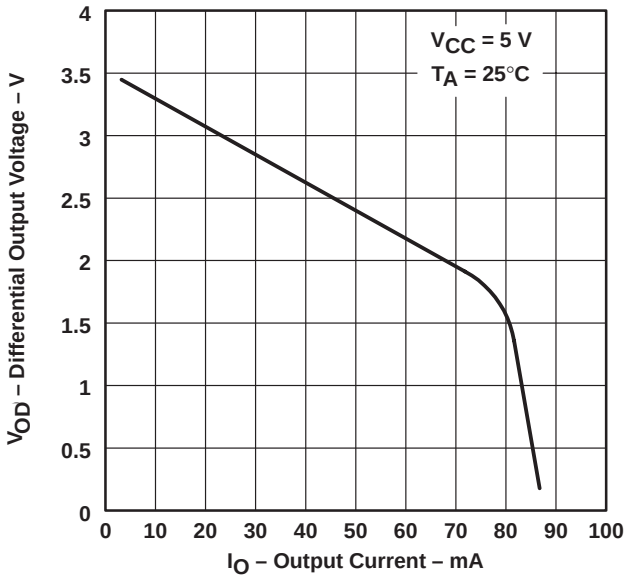


Figure 10

TYPICAL CHARACTERISTICS

RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

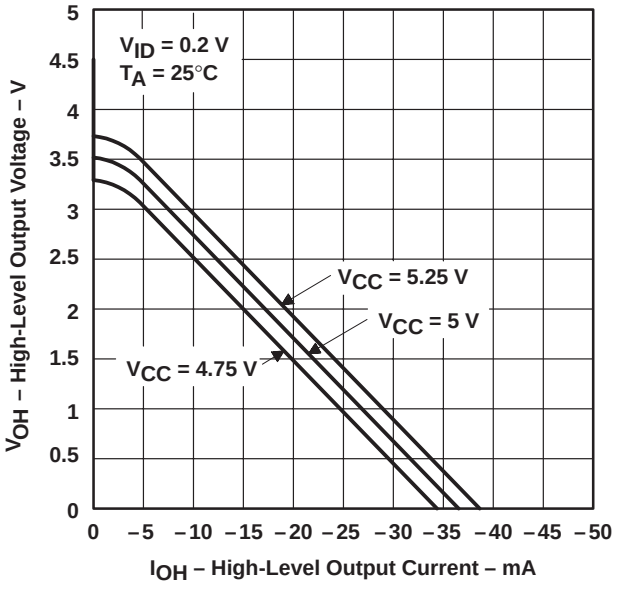
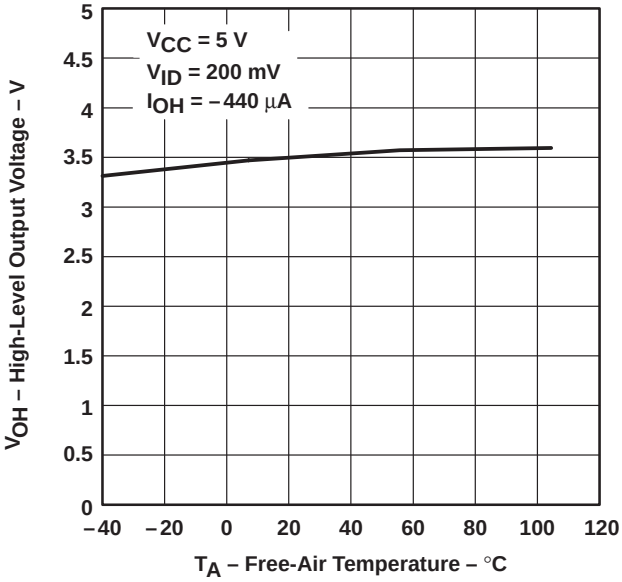


Figure 11

RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE†



† Only the 0°C to 70°C portion of the curve applies to the SN75176B.

Figure 12

RECEIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

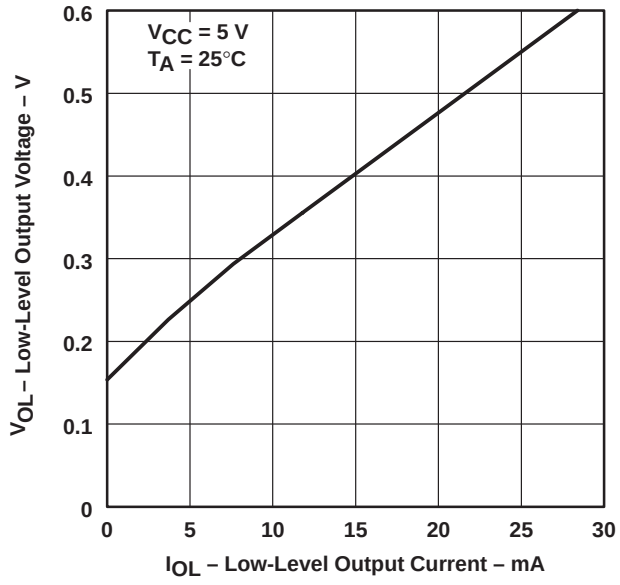


Figure 13

RECEIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

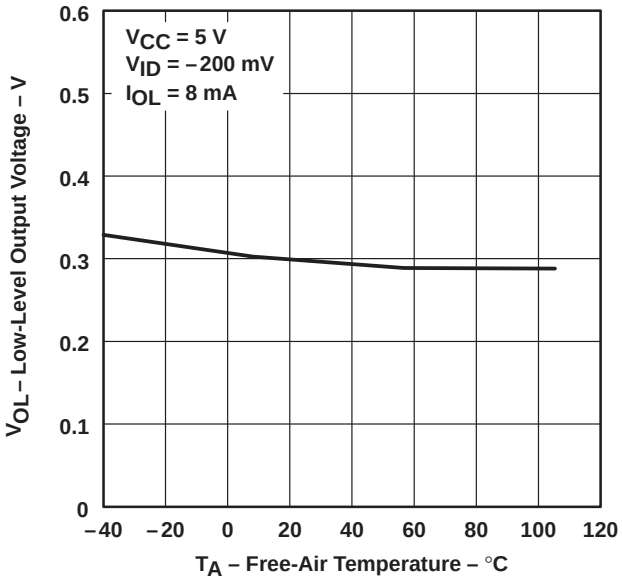


Figure 14

TYPICAL CHARACTERISTICS

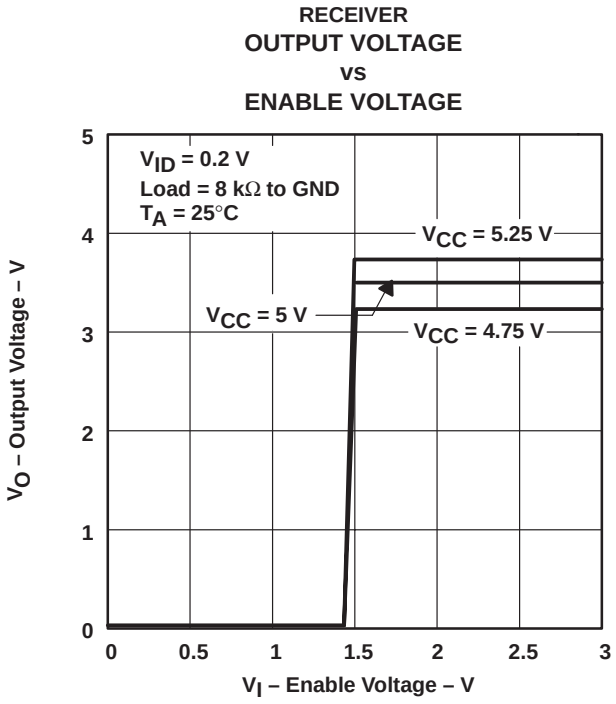


Figure 15

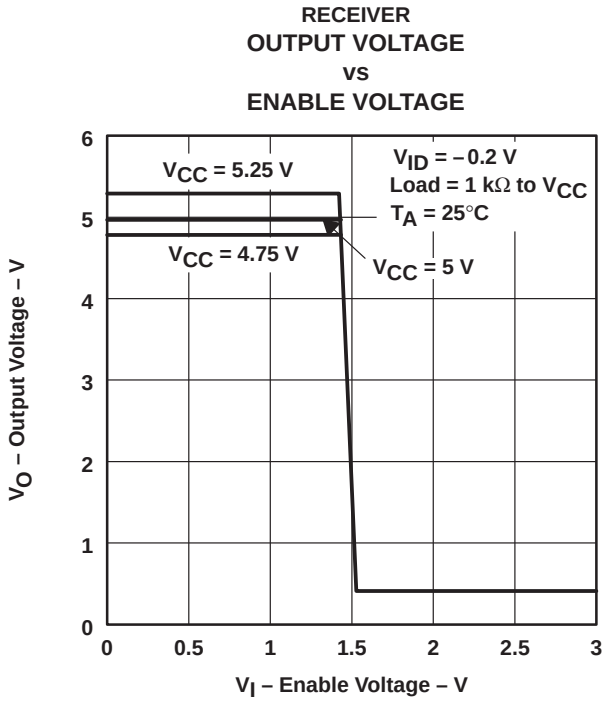
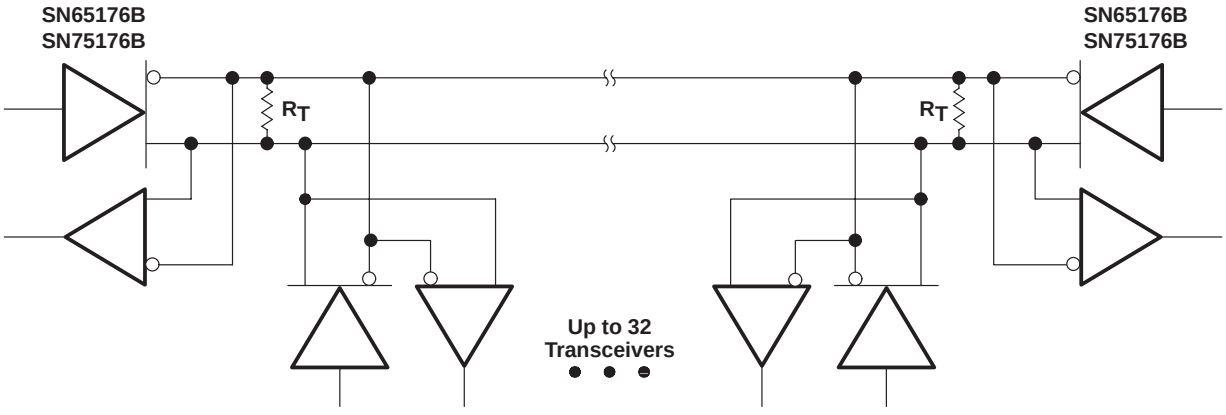


Figure 16

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible.

Figure 17. Typical Application Circuit

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